ENGINEERING

PRODUCT SPECIFICATION

SPEC.NO.: SPCH070A

DEPT.

For 2.00 mm (.079") Board to Board Connectors of System CH11

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

EIA 364 Test methods for electrical connectors

J-STD-020 Resistance to soldering Temperature for through hole Mounted Devices SS-00254 Test methods for electronic components ,LEAD-FREE soldering Part design

standards

3. APPLICABLE SERIES NO.: CH11**1NB00-0M

CH11**1NB00-TM

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

 $0.8 \text{ mm} (.031'') \sim 1.6 \text{ mm} (.063'')$



REVIEWED: <u>Eisley</u> APPROVED: <u>Eisley</u> VERIFIED: <u>Sandy</u>.



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		2A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 20 m Ω
7.3	Dielectric strength	When applied AC 500 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 M Ω

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Apply axial pull out force at 25 ± 3 mm/min on the assembly in the housing	More than 0.8 Kgf

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Cold Resistance	-40°C ± 3°C, 96 hours	Appearance: No damage
			Contact resistance:
			\triangle 20 m Ω change
9.2	Heat Resistance	105°C ± 3°C, 96 hours	Appearance: No damage
			Contact resistance:
			\triangle 20 m Ω change
9.3	Temperature Cycling	5 cycles	Appearance: No damage
		(1) -40 °C, 30 min.	Contact resistance:
		(2)Room temp. 10-15 min.	\triangle 20 m Ω change
		(3) 105 °C, 30 min.	
		(4)Room temp. 10-15 min.	
9.4	Salt Spray	Temperature: 35± 2°C	Appearance: No damage
		Solution: 5± 1%	Contact resistance:
		Spray time: 6± 1 hours	\triangle 20 m Ω max out.
		Measurement must be taken after water rinse	



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	ITEM	TEST CONDITION	REQUIREMENT
9.5	Solder ability	Soldering time: 3 ± 0.5 sec Soldering pot: 240 ± 5°C	Minimum: 95% of immersed area
9.6	Resistance to soldering heat	Soldering time: 7 ± 3 sec Soldering pot: 255 ± 5°C Refer Reflow temperature profile(11.1)	No damage

10. OPERATING TEMPERATURE: -40°C to + 105°C

- 11. Recommended IR Reflow Temperature Profile:
 - 11.1 Using Lead-Free Solder Paste

